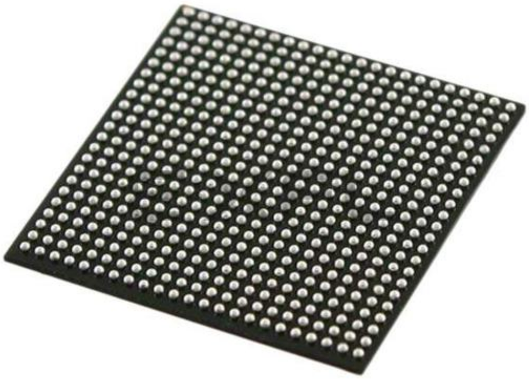
Intel - 5CGTFD5C5U19A7N Datasheet



Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Active
Number of LABs/CLBs	29080
Number of Logic Elements/Cells	77000
Total RAM Bits	5001216
Number of I/O	224
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 125°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cgtfd5c5u19a7n

Contents

Cyclone V Device Overview

The Cyclone® V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues
Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	• Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks • Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	• 8-input adaptive logic module (ALM) • Up to 13.59 megabits (Mb) of embedded memory • Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	• 3.125 gigabits per second (Gbps) and 6.144 Gbps transceivers • Hard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	• Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) • Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	• Requires only two core voltages to operate • Available in low-cost wirebond packaging • Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration

Summary of Cyclone V Features

Table 2. Summary of Features for Cyclone V Devices

<table>
<tr><th>Feature</th><th colspan="2">Description</th></tr>
<tr><td>Technology</td><td colspan="2">TSMC's 28-nm low-power (28LP) process technology
1.1 V core voltage</td></tr>
<tr><td>Packaging</td><td colspan="2">Wirebond low-halogen packages
Multiple device densities with compatible package footprints for seamless migration between different device densities
RoHS-compliant and leaded(1)options</td></tr>
<tr><td>High-performance FPGA fabric</td><td colspan="2">Enhanced 8-input ALM with four registers</td></tr>
<tr><td>Internal memory blocks</td><td colspan="2">M10K—10-kilobits (Kb) memory blocks with soft error correction code (ECC)
Memory logic array block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% of the ALMs as MLAB memory</td></tr>
<tr><td rowspan="3">Embedded Hard IP blocks</td><td>Variable-precision DSP</td><td>Native support for up to three signal processing precision levels (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the same variable-precision DSP block
64-bit accumulator and cascade
Embedded internal coefficient memory
Preadder/subtractor for improved efficiency</td></tr>
<tr><td>Memory controller</td><td>DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support</td></tr>
<tr><td>Embedded transceiver I/O</td><td>PCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port</td></tr>
<tr><td>Clock networks</td><td colspan="2">Up to 550 MHz global clock network
Global, quadrant, and peripheral clock networks
Clock networks that are not used can be powered down to reduce dynamic power</td></tr>
<tr><td>Phase-locked loops (PLLs)</td><td colspan="2">Precision clock synthesis, clock delay compensation, and zero delay buffering (ZDB)
Integer mode and fractional mode</td></tr>
<tr><td>FPGA General-purpose I/Os (GPIOs)</td><td colspan="2">875 megabits per second (Mbps) LVDS receiver and 840 Mbps LVDS transmitter
400 MHz/800 Mbps external memory interface
On-chip termination (OCT)
3.3 V support with up to 16 mA drive strength</td></tr>
<tr><td>Low-power high-speed serial interface</td><td colspan="2">614 Mbps to 6.144 Gbps integrated transceiver speed
Transmit pre-emphasis and receiver equalization
Dynamic partial reconfiguration of individual channels</td></tr>
<tr><td>HPS
(Cyclone V SE, SX, and ST devices only)</td><td colspan="2">Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum frequency with support for symmetric and asymmetric multiprocessing
Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB 2.0 On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controller, NAND flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, controller area network (CAN), serial peripheral interface (SPI), I^{2}C interface, and up to 85 HPS GPIO interfaces
System peripherals—general-purpose timers, watchdog timers, direct memory access (DMA) controller, FPGA configuration manager, and clock and reset managers
On-chip RAM and boot ROM</td></tr>
</table>

continued...

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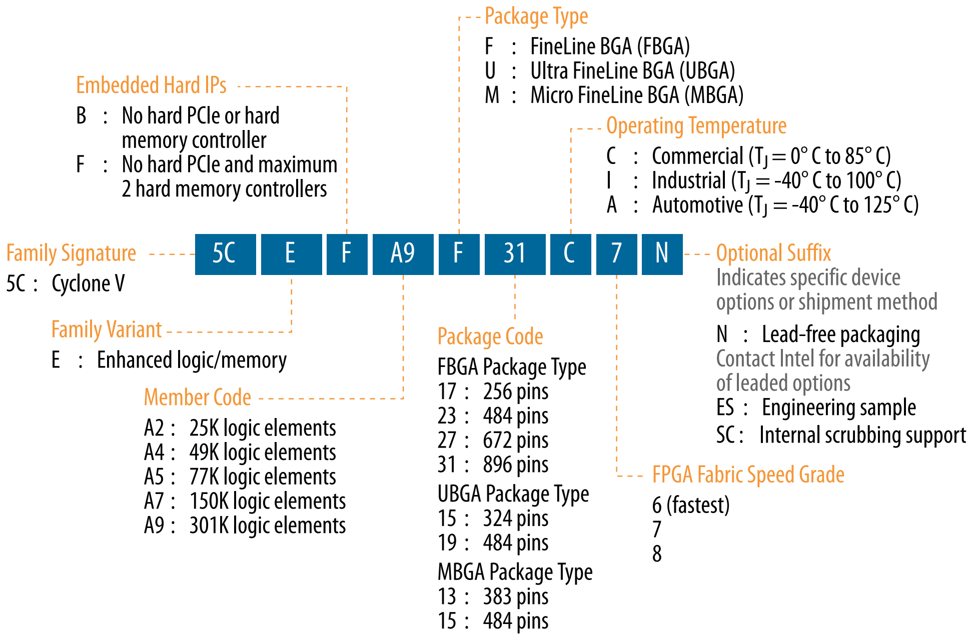
(1) Contact Intel for availability.

Available Options

Figure 1. Sample Ordering Code and Available Options for Cyclone V E Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

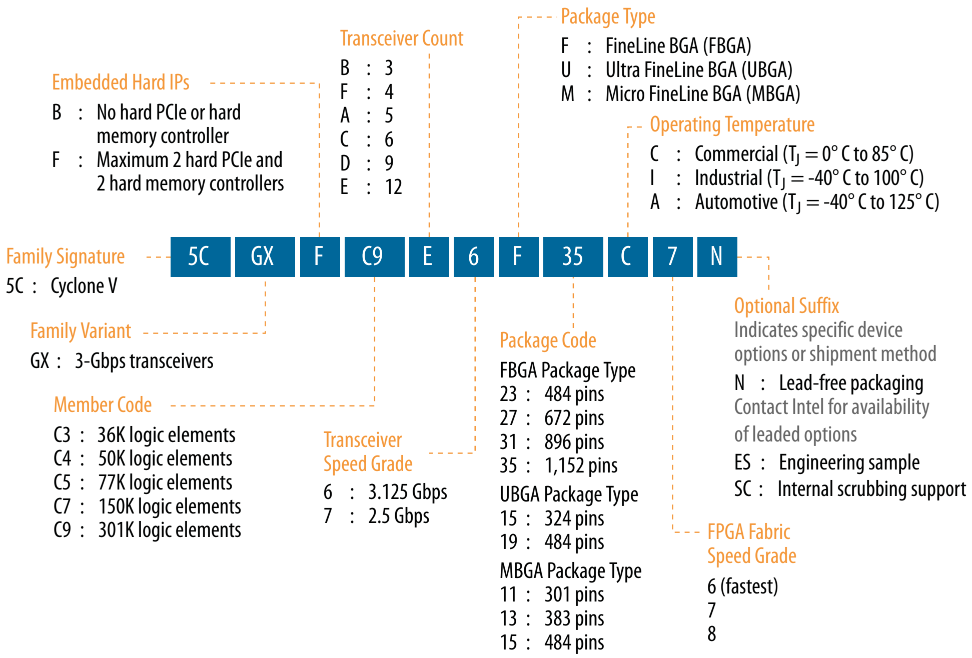
Table 4. Maximum Resource Counts for Cyclone V E Devices

Resource		**Member Code**				
		A2	**A4**	**A5**	**A7**	**A9**
Logic Elements (LE) (K)		25	49	77	150	301
ALM		9,430	18,480	29,080	56,480	113,560
Register		37,736	73,920	116,320	225,920	454,240
Memory (Kb)	M10K	1,760	3,080	4,460	6,860	12,200
	MLAB	196	303	424	836	1,717
Variable-precision DSP Block		25	66	150	156	342
18 x 18 Multiplier		50	132	300	312	684
PLL		4	4	6	7	8
GPIO		224	224	240	480	480
LVDS	Transmitter	56	56	60	120	120
	Receiver	56	56	60	120	120
Hard Memory Controller		1	1	2	2	2

Available Options

Figure 2. Sample Ordering Code and Available Options for Cyclone V GX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Maximum Resources

Table 6. Maximum Resource Counts for Cyclone V GX Devices

Resource		Member Code				
		C3	C4	C5	C7	C9
Logic Elements (LE) (K)		36	50	77	150	301
ALM		13,460	18,860	29,080	56,480	113,560
Register		53,840	75,440	116,320	225,920	454,240
Memory (Kb)	M10K	1,350	2,500	4,460	6,860	12,200
	MLAB	182	424	424	836	1,717
Variable-precision DSP Block		57	70	150	156	342
18 x 18 Multiplier		114	140	300	312	684
PLL		4	6	6	7	8
3 Gbps Transceiver		3	6	6	9	12
GPIO(4)		208	336	336	480	560

continued...

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(4) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus® Prime software, the number of user I/Os includes transceiver I/Os.

Resource		Member Code				
		C3	C4	C5	C7	C9
LVDS	Transmitter	52	84	84	120	140
	Receiver	52	84	84	120	140
PCIe Hard IP Block		1	2	2	2	2
Hard Memory Controller		1	2	2	2	2

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

Package Plan

Table 7. Package Plan for Cyclone V GX Devices

Member Code	M301 (11 mm)		M383 (13 mm)		M484 (15 mm)		U324 (15 mm)		U484 (19 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	—	—	—	—	—	—	144	3	208	3
C4	129	4	175	6	—	—	—	—	224	6
C5	129	4	175	6	—	—	—	—	224	6
C7	—	—	—	—	240	3	—	—	240	6
C9	—	—	—	—	—	—	—	—	240	5

Member Code	F484 (23 mm)		F672 (27 mm)		F896 (31 mm)		F1152 (35 mm)	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
C3	208	3	—	—	—	—	—	—
C4	240	6	336	6	—	—	—	—
C5	240	6	336	6	—	—	—	—
C7	240	6	336	9	480	9	—	—
C9	224	6	336	9	480	12	560	12

Cyclone V GT

This section provides the available options, maximum resource counts, and package plan for the Cyclone V GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide
Provides the latest information about Intel products.

Maximum Resources

Table 10. Maximum Resource Counts for Cycloneⓥ V SE Devices

Resource		Member Code			
		A2	A4	A5	A6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision DSP Block		36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Single- or dual-core	Single- or dual-core	Single- or dual-core	Single- or dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

Package Plan

Table 11. Package Plan for Cyclone V SE Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)		U672 (23 mm)		F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O	FPGA GPIO	HPS I/O
A2	66	151	145	181	—	—
A4	66	151	145	181	—	—
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181

Cyclone V SX

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

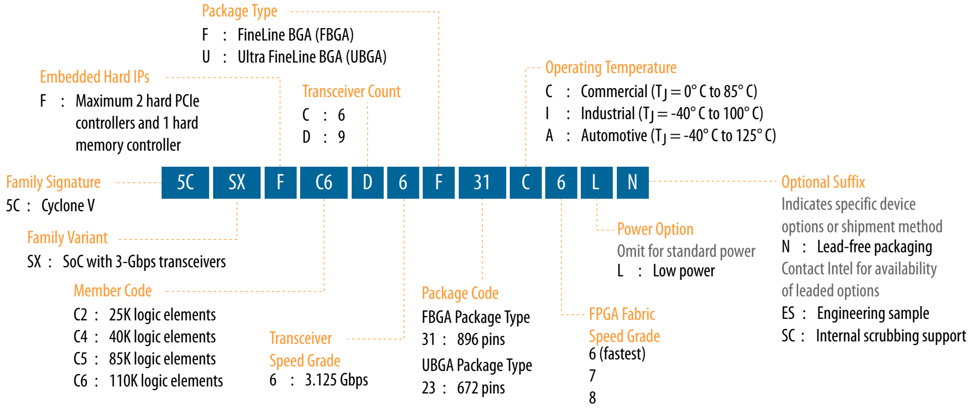
Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 5. Sample Ordering Code and Available Options for Cyclone V SX Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.



Maximum Resources

Table 12. Maximum Resource Counts for Cyclone V SX Devices

Resource		Member Code			
		C2	C4	C5	C6
Logic Elements (LE) (K)		25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precision DSP Block		36	84	87	112
18 x 18 Multiplier		72	168	174	224
FPGA PLL		5	5	6	6

continued...

Resource		Member Code			
		C2	C4	C5	C6
HPS PLL		3	3	3	3
3 Gbps Transceiver		6	6	9	9
FPGA GPIO (8)		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver	37	37	72	72
PCIe Hard IP Block		2	2	2 (9)	2 (9)
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	Dual-core	Dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices
Provides the number of LVDS channels in each device package.

Package Plan

Table 13. Package Plan for Cyclone V SX Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U672 (23 mm)			F896 (31 mm)		
	FPGA GPIO	HPS I/O	XCVR	FPGA GPIO	HPS I/O	XCVR
C2	145	181	6	—	—	—
C4	145	181	6	—	—	—
C5	145	181	6	288	181	9
C6	145	181	6	288	181	9

Cyclone V ST

This section provides the available options, maximum resource counts, and package plan for the Cyclone V ST devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

---

(8) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

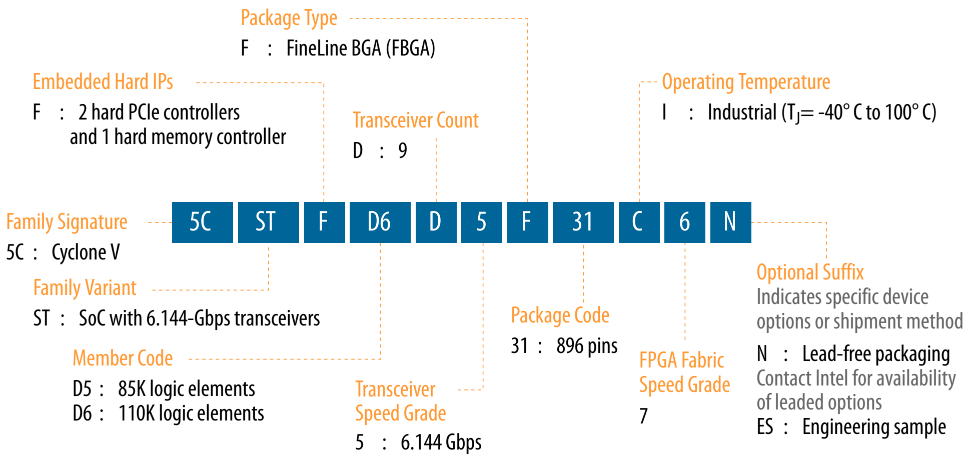
(9) 1 PCIe Hard IP Block in U672 package.

Related Information

Product Selector Guide
Provides the latest information about Intel products.

Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



Maximum Resources

Table 14. Maximum Resource Counts for Cyclone V ST Devices

Resource		Member Code	
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver		9	9
FPGA GPIO(10)		288	288
HPS I/O		181	181
LVDS	Transmitter	72	72

continued...

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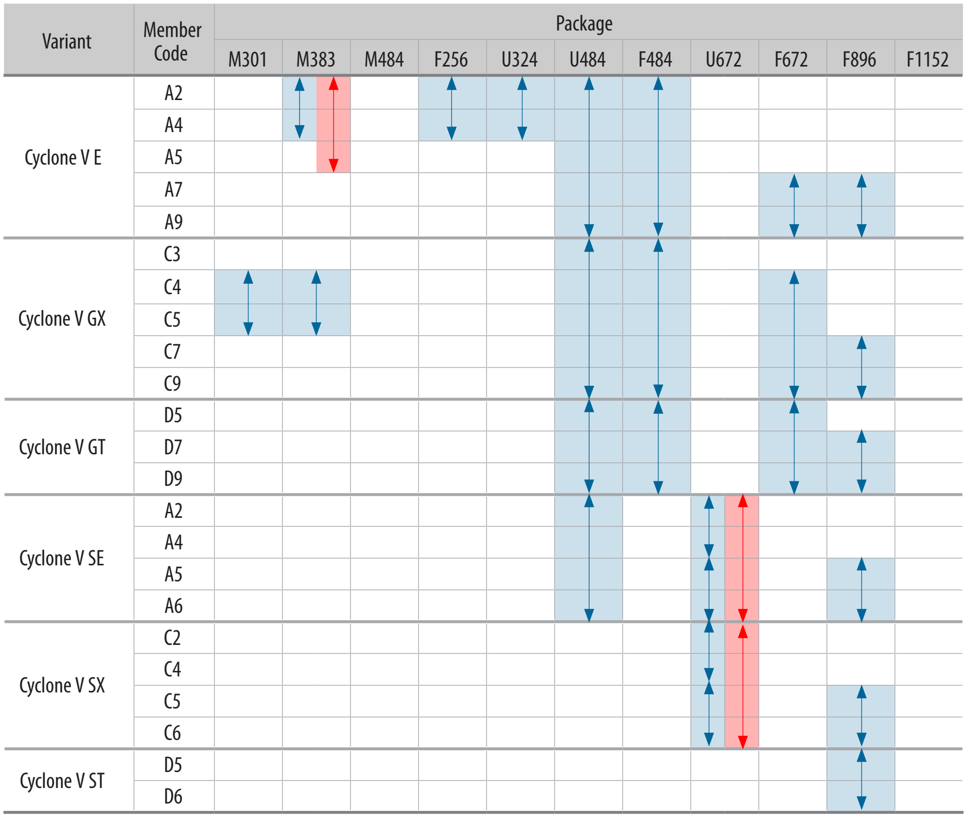
(10) The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

I/O Vertical Migration for Cyclone V Devices

Figure 7. Vertical Migration Capability Across Cyclone V Device Packages and Densities

The arrows indicate the vertical migration paths. The devices included in each vertical migration path are shaded. You can also migrate your design across device densities in the same package option if the devices have the same dedicated pins, configuration pins, and power pins.



Variant	Member Code	Package										
		M301	M383	M484	F256	U324	U484	F484	U672	F672	F896	F1152
Cyclone V E	A2		▨ 🟥		▨	▨	▨	▨				
	A4		▨ 🟥		▨	▨	▨	▨				
	A5		🟥				▨	▨				
	A7						▨	▨		▨	▨	
	A9						▨	▨		▨	▨	
Cyclone V GX	C3						▨	▨				
	C4	▨	▨				▨	▨		▨		
	C5	▨	▨				▨	▨		▨		
	C7						▨	▨		▨	▨	
	C9						▨	▨		▨	▨	
Cyclone V GT	D5						▨	▨		▨		
	D7						▨	▨		▨	▨	
	D9						▨	▨		▨	▨	
Cyclone V SE	A2						▨		▨ 🟥			
	A4						▨		▨ 🟥			
	A5						▨		▨ 🟥		▨	
	A6						▨		▨ 🟥		▨	
Cyclone V SX	C2								▨ 🟥			
	C4								▨ 🟥			
	C5								▨ 🟥		▨	
	C6								▨ 🟥		▨	
Cyclone V ST	D5										▨	
	D6										▨	

You can achieve the vertical migration shaded in red if you use only up to 175 GPIOs for the M383 package, and 138 GPIOs for the U672 package. These migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

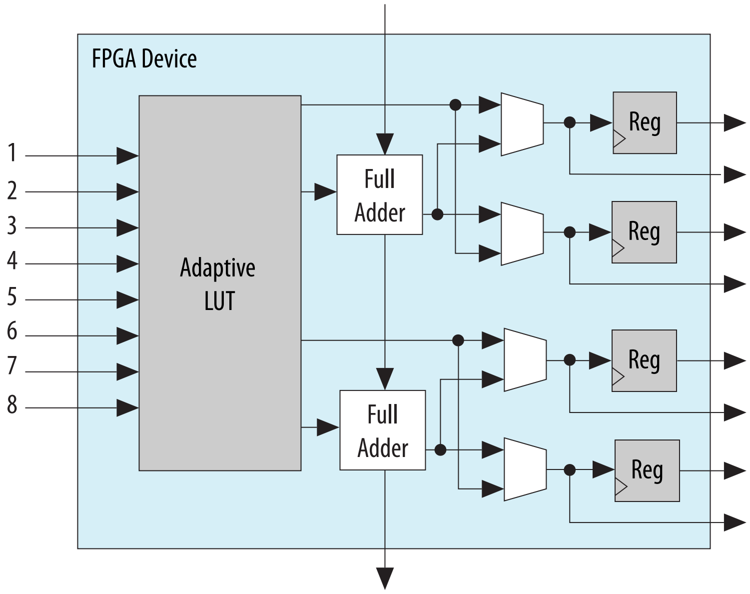
Note: To verify the pin migration compatibility, use the Pin Migration View window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

Cyclone V devices use a 28 nm ALM as the basic building block of the logic fabric.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than previous generations.

Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Cyclone V Devices on page 21
Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiply-accumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software

Variant	Member Code	Variable-precision DSP Block	Independent Input and Output Multiplications Operator			18 x 18 Multiplier Adder Mode	18 x 18 Multiplier Adder Summed with 36 bit Input
			9 x 9 Multiplier	18 x 18 Multiplier	27 x 27 Multiplier		
	C6	112	336	224	112	112	112
Cyclone V ST	D5	87	261	174	87	87	87
	D6	112	336	224	112	112	112

Embedded Memory Blocks

The embedded memory blocks in the devices are flexible and designed to provide an optimal amount of small- and large-sized memory arrays to fit your design requirements.

Types of Embedded Memory

The Cyclone V devices contain two types of memory blocks:

- 10 Kb M10K blocks—blocks of dedicated memory resources. The M10K blocks are ideal for larger memory arrays while still providing a large number of independent ports.
- 640 bit memory logic array blocks (MLABs)—enhanced memory blocks that are configured from dual-purpose logic array blocks (LABs). The MLABs are ideal for wide and shallow memory arrays. The MLABs are optimized for implementation of shift registers for digital signal processing (DSP) applications, wide shallow FIFO buffers, and filter delay lines. Each MLAB is made up of ten adaptive logic modules (ALMs). In the Cyclone V devices, you can configure these ALMs as ten 32 x 2 blocks, giving you one 32 x 20 simple dual-port SRAM block per MLAB.

Embedded Memory Capacity in Cyclone V Devices

Table 18. Embedded Memory Capacity and Distribution in Cyclone V Devices

Variant	Member Code	M10K		MLAB		Total RAM Bit (Kb)
		Block	RAM Bit (Kb)	Block	RAM Bit (Kb)	
Cyclone V E	A2	176	1,760	314	196	1,956
	A4	308	3,080	485	303	3,383
	A5	446	4,460	679	424	4,884
	A7	686	6,860	1338	836	7,696
	A9	1,220	12,200	2748	1,717	13,917
Cyclone V GX	C3	135	1,350	291	182	1,532
	C4	250	2,500	678	424	2,924
	C5	446	4,460	678	424	4,884
	C7	686	6,860	1338	836	7,696
	C9	1,220	12,200	2748	1,717	13,917

continued...

PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- LVDS output buffer with programmable differential output voltage (V_{OD}) and programmable pre-emphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture

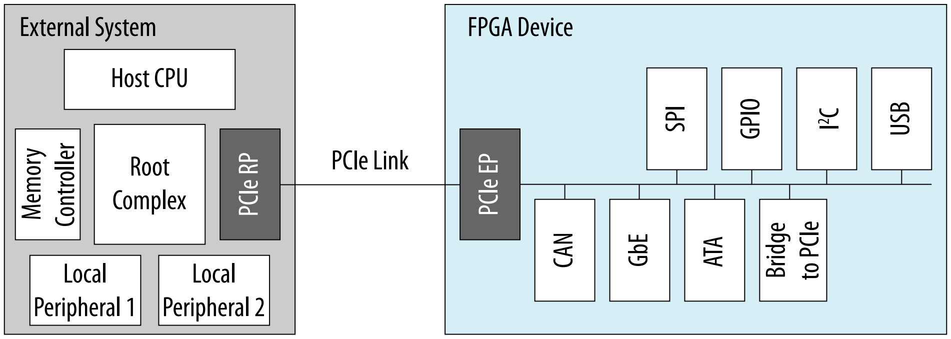
PCIe Gen1 and Gen2 Hard IP

Cyclone V GX, GT, SX, and ST devices contain PCIe hard IP that is designed for performance and ease-of-use. The PCIe hard IP consists of the MAC, data link, and transaction layers.

The PCIe hard IP supports PCIe Gen2 and Gen1 end point and root port for up to x4 lane configuration. The PCIe Gen2 x4 support is PCIe-compatible.

The PCIe endpoint support includes multifunction support for up to eight functions, as shown in the following figure. The integrated multifunction support reduces the FPGA logic requirements by up to 20,000 LEs for PCIe designs that require multiple peripherals.

Figure 9. **PCIe Multifunction for Cyclone V Devices**



The Cyclone V PCIe hard IP operates independently from the core logic. This independent operation allows the PCIe link to wake up and complete link training in less than 100 ms while the Cyclone V device completes loading the programming file for the rest of the device.

In addition, the PCIe hard IP in the Cyclone V device provides improved end-to-end datapath protection using ECC.

External Memory Interface

This section provides an overview of the external memory interface in Cyclone V devices.

Hard and Soft Memory Controllers

Cyclone V devices support up to two hard memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices. Each controller supports 8 to 32 bit components of up to 4 gigabits (Gb) in density with two chip selects and optional ECC. For the Cyclone V SoC devices, an additional hard memory controller in the HPS supports DDR3, DDR2, and LPDDR2 SDRAM devices.

All Cyclone V devices support soft memory controllers for DDR3, DDR2, and LPDDR2 SDRAM devices for maximum flexibility.

External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage (V)	Maximum Frequency (MHz)		Minimum Frequency (MHz)
		Hard Controller	Soft Controller	
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry’s lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	• Custom PHY IP core with preset feature • Electrical idle	• Custom PHY IP core with preset feature • Signal detect • Wider spread of asynchronous SSC
CPRI 4.1(16)	0.6144 to 6.144	• Dedicated deterministic latency PHY IP core • Transmitter (TX) manual bit-slip mode	• Dedicated deterministic latency PHY IP core • Receiver (RX) deterministic latency state machine
OBSAI RP3	0.768 to 3.072		
V-by-One HS	Up to 3.75	Custom PHY IP core	• Custom PHY IP core • Wider spread of asynchronous SSC
DisplayPort 1.2(17)	1.62 and 2.7		

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

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(16) High-voltage output mode (1000-BASE-CX) is not supported.

(17) Pending characterization.

Note: Although the FPGA fabric and HPS are on separate power domains, the HPS must remain powered up during operation while the FPGA fabric can be powered up or down as required.

Related Information

Cyclone V Device Family Pin Connection Guidelines
Provides detailed information about power supply pin connection guidelines and power regulator sharing.

Hardware and Software Development

For hardware development, you can configure the HPS and connect your soft logic in the FPGA fabric to the HPS interfaces using the Platform Designer (Standard) system integration tool in the Intel Quartus Prime software.

For software development, the Arm-based SoC devices inherit the rich software development ecosystem available for the Arm Cortex-A9 MPCore processor. The software development process for Intel SoCs follows the same steps as those for other SoC devices from other manufacturers. Support for Linux, VxWorks®, and other operating systems is available for the SoCs. For more information on the operating systems support availability, contact the Intel sales team.

You can begin device-specific firmware and software development on the Intel SoC Virtual Target. The Virtual Target is a fast PC-based functional simulation of a target development system—a model of a complete development board that runs on a PC. The Virtual Target enables the development of device-specific production software that can run unmodified on actual hardware.

Related Information

International Altera Sales Support Offices

Dynamic and Partial Reconfiguration

The Cyclone V devices support dynamic reconfiguration and partial reconfiguration.

Dynamic Reconfiguration

The dynamic reconfiguration feature allows you to dynamically change the transceiver data rates, PMA settings, or protocols of a channel, without affecting data transfer on adjacent channels. This feature is ideal for applications that require on-the-fly multiprotocol or multirate support. You can reconfigure the PMA and PCS blocks with dynamic reconfiguration.

Partial Reconfiguration

Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Partial reconfiguration allows you to reconfigure part of the device while other sections of the device remain operational. This capability is important in systems with critical uptime requirements because it allows you to make updates or adjust functionality without disrupting services.

Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	• Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the *Sample Ordering Code and Available Options* diagrams. • Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	• Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to –7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	• Added descriptions to package plan tables for Cyclone V GT and ST devices. • Changed instances of *Quartus II* to *Quartus Prime*.
June 2015	2015.06.12	• Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. • Updated logic elements (LE) (K) for the following devices: — Cyclone V E A7: Updated from 149.5 to 150 — Cyclone V GX C3: Updated from 35.5 to 36 — Cyclone V GX C7: Updated from 149.7 to 150 — Cyclone V GT D7: Updated from 149.5 to 150 • Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: — Cyclone V GX C3: Updated from 291 to 182 — Cyclone V GX C4: Updated from 678 to 424 — Cyclone V GX C5: Updated from 678 to 424 — Cyclone V GX C7: Updated from 1,338 to 836 — Cyclone V GX C9: Updated from 2,748 to 1,717

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Date	Version	Changes
		• Updated MLAB RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: — Cyclone V GX C3: Updated from 181 to 182 — Cyclone V GX C4: Updated from 295 to 424 • Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: — Cyclone V GX C3: Updated from 1,531 to 1,532 — Cyclone V GX C4: Updated from 2,795 to 2,924 • Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: — Cyclone V GX C4: Updated from 472 to 678 — Cyclone V GX C5: Updated from 679 to 678
March 2015	2015.03.31	• Added internal scrubbing feature under configuration in Summary of Features for Cyclone V Devices table. • Added optional suffix "SC: Internal scrubbing support" to the following diagrams: — Sample Ordering Code and Available Options for Cyclone V E Devices — Sample Ordering Code and Available Options for Cyclone V GX Devices — Sample Ordering Code and Available Options for Cyclone V SE Devices — Sample Ordering Code and Available Options for Cyclone V SX Devices
January 2015	2015.01.23	• Updated Sample Ordering Code and Available Options for Cyclone V ST Devices figure because Cyclone V ST devices are only available in I temperature grade and –7 speed grade. — Operating Temperature: Removed C and A temperature grades — FPGA Fabric Speed Grade: Removed –6 and –8 speed grades • Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: — Device Variants for the Cyclone V Device Family table — Sample Ordering Code and Available Options for Cyclone V ST Devices figure — Maximum Resource Counts for Cyclone V ST Devices • Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. — Logic elements (LE) (K): Updated from 35.7 to 35.5 — Variable-precision DSP block: Updated from 51 to 57 — 18 x 18 multiplier: Updated from 102 to 114 • Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. — Variableprecision DSP Block: Updated from 51 to 57 — 9 x 9 Multiplier: Updated from 153 to 171 — 18 x 18 Multiplier: Updated from 102 to 114 — 27 x 27 Multiplier: Updated from 51 to 57 — 18 x 18 Multiplier Adder Mode: Updated from 51 to 57 — 18 x 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 • Updated Embedded Memory Capacity and Distribution in Cyclone V Devices table for Cyclone V GX G3 devices. — M10K block: Updated from 119 to 135 — M10K RAM bit (Kb): Updated from 1,190 to 1,350 — MLAB block: Updated from 255 to 291 — MLAB RAM bit (Kb): Updated from 159 to 181 — Total RAM bit (Kb): Updated from 1,349 to 1,531
October 2014	2014.10.06	Added a footnote to the "Transceiver PCS Features for Cyclone V Devices" table to show that PCIe Gen2 is supported for Cyclone V GT and ST devices.

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